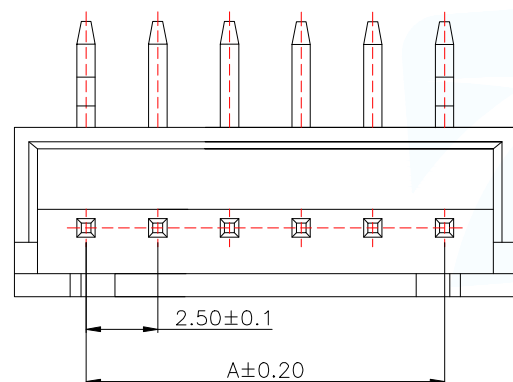
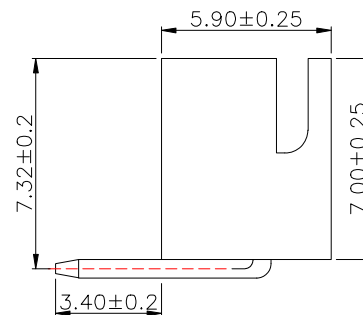
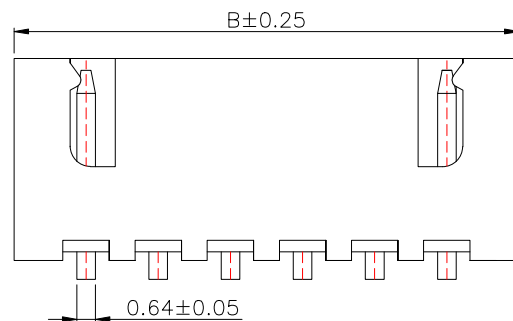


SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10\text{m}\Omega$
4. 绝缘电阻: $\geq 100\text{M}\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求。

Part No	Pin	A	B
WAFER-XH2.54-2PWZ	2	2.50	7.50
WAFER-XH2.54-3PWZ	3	5.00	10.00
WAFER-XH2.54-4PWZ	4	7.50	12.50
WAFER-XH2.54-5PWZ	5	10.00	15.00
WAFER-XH2.54-6PWZ	6	12.50	17.50
WAFER-XH2.54-7PWZ	7	15.00	20.00
WAFER-XH2.54-8PWZ	8	17.50	22.50
WAFER-XH2.54-9PWZ	9	20.00	25.00
WAFER-XH2.54-10PWZ	10	22.50	27.50
WAFER-XH2.54-11PWZ	11	25.00	30.00
WAFER-XH2.54-12PWZ	12	27.50	32.50
WAFER-XH2.54-13PWZ	13	30.00	35.00
WAFER-XH2.54-14PWZ	14	32.50	37.50
WAFER-XH2.54-15PWZ	15	35.00	40.00
WAFER-XH2.54-16PWZ	16	37.50	42.50
WAFER-XH2.54-17PWZ	17	40.00	45.00
WAFER-XH2.54-18PWZ	18	42.50	47.50
WAFER-XH2.54-19PWZ	19	45.00	50.00
WAFER-XH2.54-20PWZ	20	47.50	52.50

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡80u"MIN
1	基座Wafer	PA66(UL94 V-0)	1	白色
序号	名称	材料	数量	备注
MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd		
UNLESS OTHERWISE SPECIFIED TOLERANCES		 TITLE: WAFER XH2.54MM 弯针		
DECIMALS:	ANGLES:	PAR	WAFER-XH2.54-NPWZ	
.X±0.20	±2°	DWN		
.XX±0.10		CHKD		
.XXX±0.05		APVD		
CUSTOMER COPY		SCALE 1:1	UNIT: MM	
		SIZE: A4	SHEET: 1F1	REV: A